



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-08-21
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EU6S*6395AAL	A	Z8GA	2018-08-21
Amount	UoM	Unit type	ST ECOPACK Grade	
54.50	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminat	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5X4.4X0.9	16	gull wing	
Comment	65 TSSOP 16 BODY 4.4 PITCH 0.65; MDF valid for TSV6395IPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EU65*6395AAL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.178	mg	supplier	die	Silicon (Si)	7440-21-3		1.139	mg	966893	20899
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	8489	183
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	849	18
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	849	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2547	55
Leadframe	Copper & its alloys	19.703	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	20374	440
				supplier	alloy	Copper (Cu)	7440-50-8		18.605	mg	944272	341376
				supplier	alloy	Nickel (Ni)	7440-02-0		0.621	mg	31518	11394
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.032	mg	1624	587
				supplier	alloy	Silicon (Si)	7440-21-3		0.138	mg	7004	2532
Die attach	Other Organic Materials	0.514	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.307	mg	15581	5633
				supplier	glue	Silver(Ag)	7440-22-4		0.401	mg	780156	7358
				supplier	glue	Acrylate monomer	Proprietary		0.093	mg	180934	1706
				supplier	glue	Polybutadiene diacrylate	Proprietary		0.010	mg	19455	183
				supplier	glue	Epoxy resin	25068-38-6		0.010	mg	19455	183
Bonding wires	Precious metals	0.216	mg	supplier	wire	Gold (Au)	7440-57-5		0.216	mg	1000000	3963
Encapsulation	Other Organic Materials	32.672	mg	supplier	mold compound	Amorphous silica	60676-86-0		27.645	mg	846137	507248
				supplier	mold compound	Crystal silica	14808-60-7		0.969	mg	29658	17780
				supplier	mold compound	Epoxy resin-1	Proprietary		0.584	mg	17875	10716
				supplier	mold compound	Epoxy resin-2	25068-38-6		1.299	mg	39759	23835
				supplier	mold compound	Phenol Resin	29690-82-2		0.065	mg	1989	1193
Finishing	Other inorganic materials	0.217	mg	supplier	mold compound	Carbon Black	1333-86-4		2.110	mg	64581	38716
				supplier	Connection coating	Tin (Sn)	7440-31-5		0.217	mg	1000000	3982